

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

HENRY CHUNG

Docket: 30-4718 (4780)

Serial Number: 09/328,645

Group Art Unit: 2811

Filed: June 9, 1999

Examiner: H. Vu

For: A FABRICATION METHOD OF INTEGRATED CIRCUITS WITH  
BORDERLESS VIAS AND LOW DIELECTRIC-CONSTANT INTER-METAL  
DIELECTRICS

AMENDMENT**FAX COPY RECEIVED**

SEP 23 2002

TECHNOLOGY CENTER 2800

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 3, 2002, please amend the above identified  
patent application as follows:

In the Specification:

CLEAN COPY OF SPECIFICATION PARAGRAPH

On page 1, in the Title :

INTEGRATED CIRCUITS WITH BORDERLESS VIAS AND  
LOW DIELECTRIC-CONSTANT INTER-METAL DIELECTRICS

In the claims:

CLEAN COPY OF AMENDED CLAIMS

1. (Amended) An integrated circuit structure which comprises
- (a) a substrate;
  - (b) a layer of a first polymeric dielectric material on the substrate;

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For: A FABRICATION METHOD OF INTEGRATED CIRCUITS WITH BORDERLESS  
VIAS AND LOW DIELECTRIC-CONSTANT INTER-METAL DIELECTRICS#15/A  
9/26/02  
JumFAX COVER SHEETTO: Commissioner for Patents  
Washington, D.C. 20231

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FROM: Richard S. Roberts  
Reg. No. 27941  
P.O. Box 484  
Princeton, New Jersey 08542  
(609) 921-3500**FAX COPY RECEIVED**

SEP 23 2002

TECHNOLOGY CENTER 2800

DATE: September 23, 2002

KINDLY DIRECT THIS COMMUNICATION TO:

EXAMINER : H. Vu  
GROUP : 2811NO. OF PAGES SENT INCLUDING THIS COVER SHEET: 16

If all pages are not received, please call (609) 921-3500.